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(54) **MODULAR MEMORY DEVICES**

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ABSTRACT

The present application provides a memory device. The memory device includes a connector plate having a front edge and a rear edge opposite to the front edge, wherein the connector plate comprises an edge connector disposed at the rear edge and configured to connect to a host connector of a host device; a controller plate defining a first connection region, a second connection region and a chip region, wherein the controller plate is attached to the connector plate at the first connection region, and the controller plate comprises a memory control module disposed in the chip region and in electrical communication with the edge connector; and at least one memory module detachably connected to the controller plate at the second connection region of the controller plate, wherein each of the at least one memory module is in electrical communication with the memory control module when the memory module is connected to the controller plate, such that the memory module can be accessible by the host device via the memory control module.

